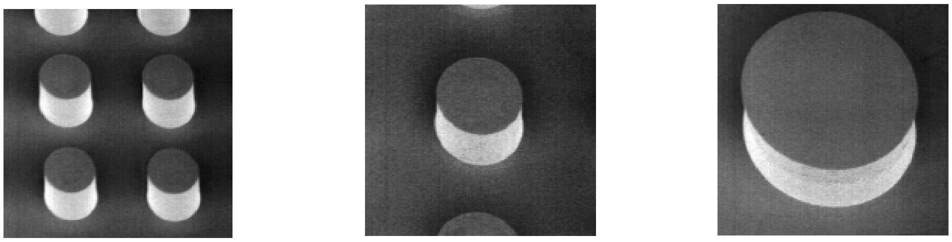
Thick Chemically Amplified i-line Photoresists

PRODUCT DESCRIPTION

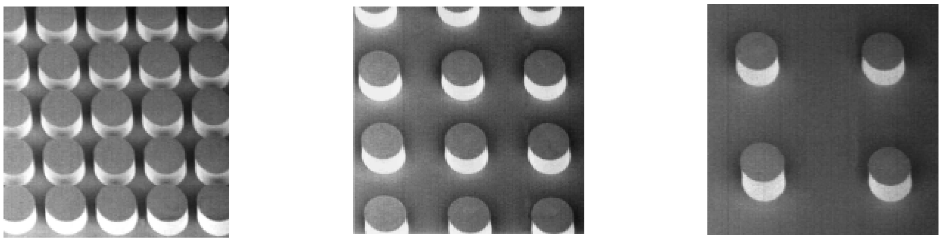
Shin-Etsu SIPR™-7120 Series is a family of spin-on, chemically amplified positive i-line photoresists formulated to achieve the thick coatings needed for solder bump or copper pillar plating. The SIPR-7120 Series is characterized by low dose requirements, wide process windows at today's critical dimensions, good plating resistance, and extendability to feature sizes well below current technology.

PROPERTIES

- i-line sensitive (broadband tool OK)
- Positive tone
- Chemically-amplified for faster photospeeds
- Capable of 10-100µm in a single coat
- No PEB required
- TMAH developable
- Good plating resistance
- Easily stripped



30µm pillars　50µm pillars　100µm pillars



50µm pillars (1:4)　50µm pillars (1:1)　50µm pillars (2:1)

Copper Pillars After Resist Strip
Thickness = 55µm

Revision 2.3

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